# Using the UCC28610EVM-474

# **User's Guide**



Literature Number: SLUU383C November 2009–Revised June 2011



## UCC28610EVM-474 25-W Universal Off-Line Flyback Converter

#### 1 Introduction

The UCC28610EVM-474 evaluation module is a 25-W off-line Discontinuous Mode (DCM) flyback converter providing 12 V at 2.1-A maximum load current, operating from a universal AC input. The module is controlled with the UCC28610 Green-Mode Flyback Controller which uses a cascoded architecture that allows fully integrated current control without an external sense resistor. The converter maintains discontinuous mode operation over the entire operating range. This innovative approach results in efficiency, reliability, and system cost improvements over a conventional flyback.

## 2 Description

This evaluation module uses the UCC28610 Green-Mode Flyback Controller (TI Literature Number SLUS888) in a 25-W DCM flyback converter that exceeds Energy Star™ EPS version 2.0 for efficiency during active load and no-load power consumption. The input accepts a voltage range of 85 V<sub>AC</sub> to 265 V<sub>AC</sub>. The output provides a regulated output voltage of 12 V<sub>DC</sub> at a load current of up to 2.1 A. The converter will transition through three operating modes: green mode (GM), amplitude modulation (AM), and frequency modulation (FM), depending upon the power level and FB current. In FM mode, the on-time is fixed, resulting in a fixed peak primary current at each cycle, and the switching frequency is increased with increasing load. In AM mode, the switching frequency is fixed at 30 kHz and the peak primary current is modulated with the on-time as with any typical PWM controller. Green mode operation at light load consists of burst packets of 30-kHz pulses with a fixed on-time and peak primary currents of 33% of the maximum programmed level. Low system parts count and built in advanced protection features result in a cost-effective solution that meets stringent world-wide energy efficiency requirements.

This user's guide provides the schematic, component list, assembly drawing, art work, and test set up necessary to evaluate the UCC28610 in a typical off-line converter application.



Description www.ti.com

## 2.1 Applications

The UCC28610 is suited for use in isolated off-line systems requiring high efficiency and advanced fault protection features including:

- AC/DC Adaptors that have a Peak Power Output of 12 W to 65 W
- · Housekeeping and Auxiliary Power Supplies
- Off-line Battery Chargers
- Consumer Electronics (DVD players, set-top boxes, gaming, printers, etc.)

#### 2.2 Features

The UCC28610EVM-474 features include:

- Isolated 25 W, 12-V output
- Universal Off-Line Input Voltage Range
- Exceeds Energy Star™ EPS Version 2.0 Requirements for Active Load Efficiency and No-Load Power Consumption
- Cascoded Configuration Allows Fully Integrated Current Control Without an External Sense Resistor
- · Multiple Operating Modes for Optimum Efficiency Over entire Operating Range
- Over Current Protection to Limit RMS Input and Output Current
- Timed overload with Shutdown/Retry Response
- · Opto-Less Output Overload Protection

#### **CAUTION**

High voltage levels are present on the evaluation module whenever it is energized. Proper precautions must be taken when working with the EVM. The large bulk capacitor, C9, and the output capacitors, C15 and C16, must be completely discharged before the EVM can be handled. Serious injury can occur if proper safety precautions are not followed.



## 3 Electrical Performance Specifications

Table 1. UCC28610EVM-474 Electrical Performance Specifications

PARAMETER		PARAMETER CONDITIONS MIN			MAX	UNITS
INPUT (	CHARACTERISTICS				l	
V <sub>IN</sub>	Input voltage		85		265	VRMS
I <sub>IN</sub>	Input current	$V_{IN} = 115 V_{RMS}, I_{OUT} = max$		0.3		Α
		V <sub>IN</sub> = 115 V <sub>RMS</sub> , I <sub>OUT</sub> = 0 A		0.03		Α
$V_{\text{UVLO}}$	Brown out	I <sub>OUT</sub> = max		72		V
OUTPU	T CHARACTERISTICS					
V <sub>OUT</sub>	Output voltage	$V_{IN}$ = min to max, $I_{OUT}$ = min to max	10.8	12	13.2	V
$V_{ripple}$	Output voltage ripple	$V_{IN} = 115 V_{RMS}, I_{OUT} = max$		80	120	mVpp
I <sub>OUT</sub>	Output current	V <sub>IN</sub> = min to max	0		2.1	Α
I <sub>OCP</sub>	Output over current inception point	V <sub>IN</sub> = max		3		Α
V <sub>OVP</sub>	Output OVP	I <sub>OUT</sub> = min to max			16	V
	Transient response voltage over shoot	I <sub>OUT</sub> = min to max		500		mV
SYSTE	M CHARACTERISTICS		1	•	'	
f <sub>SW</sub>	Switching frequency		26.3		140.4	kHz
h <sub>PEAK</sub>	Peak efficiency	V <sub>IN</sub> = 115 V <sub>RMS</sub> , I <sub>OUT</sub> = 1.05 A		85.7		%
	No load power consumption	$V_{IN} = 115 V_{RMS}$		67		mW
		$V_{IN} = 230 V_{RMS}$		107		IIIVV
	Operating temperature range	$V_{IN}$ = min to max, $I_{OUT}$ = min to max		25		°C
MECHA	NICAL CHARACTERISTICS	•	<del>'</del>	+		
Width	Dimensions			2.3		
Length				3.5		inches
Height	7	Component height			1	



## 4 Schematic/Revision Code Placement

**NOTE:** For revision A versions of the evaluation module, please refer to Appendix A of this user's guide for the schematic, list of materials and board layout. The EVM revision code can be found on the lower right corner of the top side of the board, as shown in Figure 1.

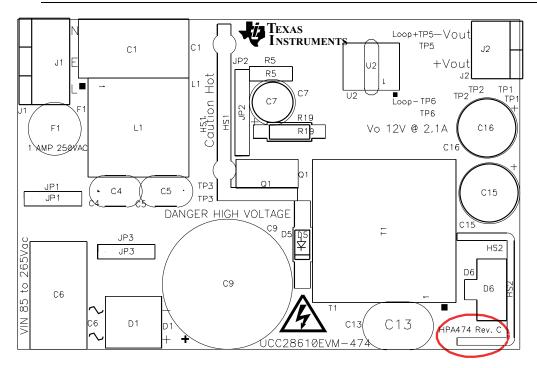


Figure 1. Placement of Revision Code for the Evaluation Module.



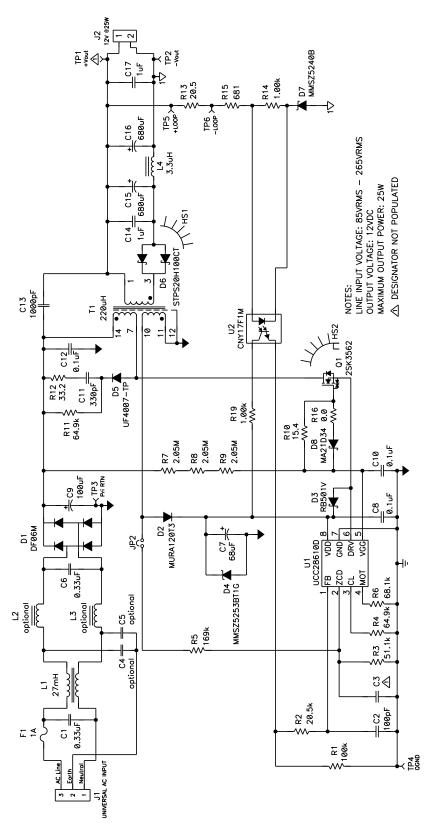


Figure 2. UCC28610EVM-474 Schematic



## 4.1 Circuit Description

A brief description of the circuit elements follows:

- Diode bridge D1, input capacitor C9, transformer (a.k.a. flyback inductor) T1, HV MOSFET Q1, UCC28610 controller U1, Schottky rectifier D6, Output capacitors C15 and C16 form the power stage of the converter. Note that the UCC28610 U1 is part of the power stage. This is because the DRV and GND pins carry the full peak primary side current of the converter.
- Capacitors C12, C14, and C17 filter the high frequency noise directly across the electrolytic input and output capacitors.
- The input EMI filter is made up of X2 capacitors, C1 and C6, and common mode inductor L1 and Y2 capacitors, C4 and C5. Excessive surge current protection is provided by a slow blow fuse, F1.
- Resistor R11, capacitor C11, and diode D5 make up the primary side voltage clamp for the HV MOSFET. The clamp prevents the drain voltage on Q1 from exceeding its maximum rating. The integrated snubber, composed of R12 and C11, reduces the ringing on the primary side windings that might inadvertently trigger the zero current detection circuit in the device.
- Resistors R7, R8, and R9 supply start up bias current to the VGG shunt regulator. Schottky diode D3
  is required to provide initial start up to VDD from VGG at start up.
- Operating bias to the controller is provided by the auxiliary winding on T1, diode D2, and bulk capacitor C7. The zener diode, D4, maintains the bias voltage on VDD below the absolute maximum rating at full load.
- Gate drive circuitry is composed of gate drive resistor R10, used for damping oscillations during turn
  on. Resistor R16 and diode D8 are required to provide a current path at turn off because the gate is
  shorted to the source of the HV MOSFET during each switching cycle. For circuits that experience high
  ringing on VGG at turn off, R16 can be replaced with a ferrite bead.
- Capacitors C8 and C10 are decoupling capacitors which should always be good quality low ESR/ESL type capacitors placed as close to the device pins as possible and returned directly to the device ground reference.
- C13 filters the common mode noise between the primary and secondary sides.
- Inductor L2, with capacitor C16, reduces the output voltage ripple.
- Resistors R5 and R3 program the over voltage threshold. Capacitor C3 can be used to add a small delay to ZCD, to align the turn on time of the primary switch with the resonant valley of the primary winding.
- Resistor R6 programs the maximum on time of the HV MOSFET.
- Resistor R4 sets the maximum value for the peak primary current.
- Resistor R2 and capacitor C2 provide a filter for the FB signal while resistor R1 ensures that the
  optocoupler emitter current can go to 0A. Resistor R19 provides a non-intrusive point to monitor the FB
  by measuring the voltage drop across R19.
- The simple output voltage feedback loop is composed of zener diode D7, resistors R14 and R15, and the optocoupler U2. Using an opto with a low CTR provides better noise immunity. Resistor R13 is used as an injection point for small signal frequency response testing.



www.ti.com EVM Test Set Up

## 5 EVM Test Set Up

Figure 2 shows the equipment set up when measuring the input power consumption during no load. Note the addition of the  $10-\Omega$  shunt resistor in Figure 3. During the no-load test, the power analyzer should be set for long averaging in order to include several cycles of operation and an appropriate current scale factor for using the external shunt must be used. Figure 3 shows the basic test set up recommended to evaluate the UCC28610EVM-474 with a load.

## **WARNING**

High voltages that may cause injury exist on this evaluation module (EVM). Please ensure all safety procedures are followed when working on this EVM. Never leave a powered EVM unattended.

## 5.1 Test Equipment

See Figure 3 and Figure 4 for recommended test set ups.

- AC Input Source: The input source shall be an isolated variable AC source capable of supplying between 85 V<sub>RMS</sub> and 265 V<sub>RMS</sub> at no less than 30 W and connected as shown in Figure 3 and Figure 4. For accurate efficiency calculations, a power meter should be inserted between the neutral line of the AC source and the Neutral terminal of the EVM. For highest accuracy, connect the voltage terminals of the power meter directly across the Line and Neutral terminals of the EVM.
- Load: For the output load, a programmable electronic load set to constant current mode and capable
  of sinking 0 to 3 A<sub>DC</sub> at 12 V<sub>DC</sub> shall be used. For highest accuracy, V<sub>OUT</sub> can be monitored by
  connecting a DC voltmeter, DMM V<sub>1</sub>, directly across the +Vout and –Vout terminals as shown in
  Figure 3 and Figure 4. A DC current meter, DMM A<sub>1</sub>, should be placed in series with the electronic
  load for accurate output current measurements.
- **Power Meter:** The power analyzer shall be capable of measuring low input current, typically less than 10 mA, and a long averaging mode if low power standby mode input power measurements are to be taken. An example of such an analyzer is the Voltech PM100 Single Phase Power Analyzer. To measure the intermittent bursts of current and power drawn from the line during no-load operation, an external 10-Ω shunt, with a current scale factor of 10 A/V, was used at a high sample rate over an extended period of time in order to display the averaged results (refer to Figure 3).
- Multimeters: Two digital multimeters are used to measure the regulated output voltage (DMM V<sub>1</sub>) and load current (DMM A<sub>1</sub>).
- Oscilloscope: A digital or analog oscilloscope with a 500-MHz scope probe is recommended.
- Fan: Forced air cooling is not required.
- Recommended Wire Gauge: a minimum of AWG18 wire is recommended. The wire connections between the AC source and the EVM, and the wire connections between the EVM and the load should be less than two feet long.



EVM Test Set Up www.ti.com

## 5.2 Recommended Test Set Up for Operation Without a Load

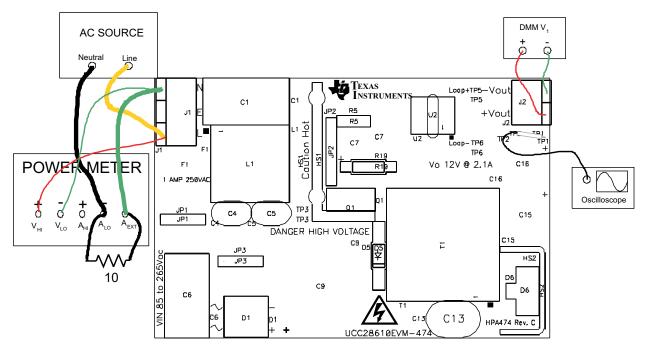


Figure 3. UCC28610EVM-474 Recommended Test Set Up Without a Load

## 5.3 Recommended Test Set Up for Operation With a Load

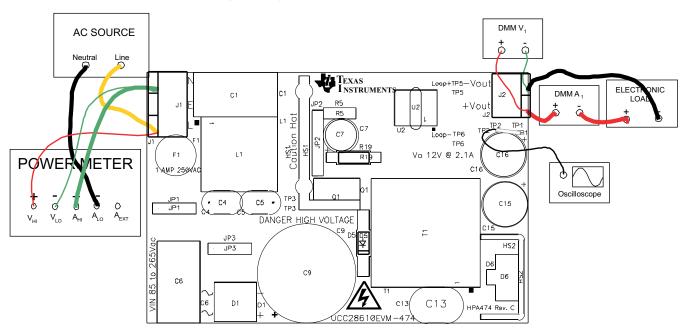


Figure 4. UCC28610EVM-474 Recommended Test Set Up With a Load



www.ti.com EVM Test Set Up

## 5.4 List of Test Points

## **Table 2. Test Point Functional Description**

TEST POINT	NAME	DESCRIPTION
TP1	+Vout	Output voltage of EVM; this designator is not populated with a pin in order to facilitate tip and barrel output ripple voltage measurements.
TP2	-Vout	Return of the output of the EVM, secondary side GND reference.
TP3	Pwr RTN	Primary side power ground
TP4	QGND	Primary side signal ground
TP5	+LOOP	Loop injection point, EVM output
TP6	-LOOP	Loop injection point
J1-1	Neutral	Neutral input from the AC source
J1-2	Earth	Earth reference from the AC source
J1-3	AC Line	Line input from AC source
J2-1	+Vout	Positive output terminal of the EVM to the load
J2-2	-Vout	Return connection of the EVM output to the load



Test Procedure www.ti.com

#### 6 Test Procedure

All tests should use the set up as described in Section 5 of this user's guide. The following test procedure is recommended primarily for power up and shutting down the evaluation module. Never leave a powered EVM unattended for any length of time.

## 6.1 Applying Power to the EVM

- 1. Set up the EVM as shown in Section 5 of this user's guide
  - (a) If no-load input power measurements are to be made, set the power analyzer to long averaging and external shunt mode. Insert a shunt, such as a  $10-\Omega$  resistor as shown in Figure 3, in series with the Neutral terminal of the EVM. Set the appropriate current scale on the power analyzer.
  - (b) For operation with a load, as shown in Figure 4, set the electronic load to constant current mode to sink 0 A.
- 2. Prior to turning on the AC source, set the voltage to between 85  $V_{AC}$  and 265  $V_{AC}$ .
- 3. Turn on the AC source.
- 4. Monitor the output voltage on DMM V<sub>1</sub>.
- 5. Monitor the output current on DMM A<sub>1</sub>.
- 6. The EVM is now ready for testing.

## 6.2 No-Load Power Consumption

- 1. Use the test set up shown in Figure 3.
  - (a) Set the power analyzer to external shunt mode.
  - (b) Set the appropriate current scale factor for using an external shunt on the power analyzer. A  $10-\Omega$  shunt scales at 10,000 mV/A for the PM100 Voltech.
  - (c) Set the power analyzer long averaging time to include several cycles of operation. The PM100 Voltech should be set to a long averaging time of 10 or more for accurate burst mode measurements.
- 2. Apply power to the EVM per Section 6.1.
- 3. Monitor the input power on the power analyzer while varying the input voltage.
- 4. Make sure the input power is off and the bulk capacitor and output capacitors are completely discharged before handling the EVM.



www.ti.com Test Procedure

## 6.3 Output Voltage Regulation and Efficiency

- 1. For load regulation:
  - (a) Use the test set up shown in Figure 4.
    - (i) Be sure to remove the external shunt from the power analyzer and set the analyzer to normal mode (not long averaging).
  - (b) Set the AC source to a constant voltage between 85  $V_{AC}$  and 265  $V_{AC}$ .
  - (c) Apply power to the EVM per Section 6.1.
  - (d) Vary the load current from 0 A up to 2.1 A, as measured on DMM A<sub>1</sub>.
  - (e) Observe that the output voltage on DMM  $V_1$  remains within 10% of 12  $V_{DC}$ .
- 2. For line regulation:
  - (a) Set the load to sink 2.1 A.
  - (b) Vary the AC source from 85  $V_{AC}$  to 265  $V_{AC}$ .
  - (c) Observe that the output voltage on DMM  $V_1$  remains within 10% of 12  $V_{DC}$ .
- Make sure the input power is off and the bulk capacitor and output capacitors are completely discharged before handling the EVM.

## 6.4 Output Voltage Ripple

- Expose the ground barrel of the scope probe. Insert the tip of the probe into the plated via located on the +Vout pad of the EVM (TP1) and lean the probe so that the exposed ground barrel is resting on the test point on the -Vout pad of the EVM (TP2) for a tip and barrel measurement as shown in the example depicted in Figure 5.
- 2. Apply power to the EVM per Section 6.1.
- 3. Monitor the output voltage ripple on the oscilloscope.

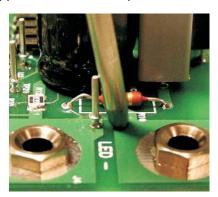


Figure 5. Typical Example of Tip and Barrel Measurement Technique

**NOTE:** This photo was not taken on the UCC28610EVM specifically but serves as a visual aid to perform the test measurement.

#### 6.5 Equipment Shutdown

- 1. Ensure the load is at maximum; this will quickly discharge the output capacitors.
- 2. Turn off the AC source.



## 7 Performance Data and Typical Characteristic Curves

Figure 6 through Figure 23 present typical performance curves for the UCC28610EVM-474.

#### EFFICIENCY vs. LOAD CURRENT

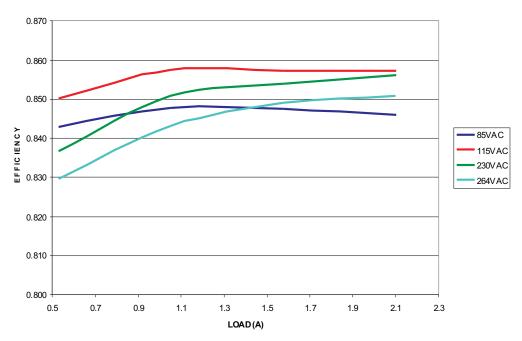


Figure 6. Efficiency as a Function of Load Current and Input Voltage

#### No-Load Power Consumption vs. Line Voltage

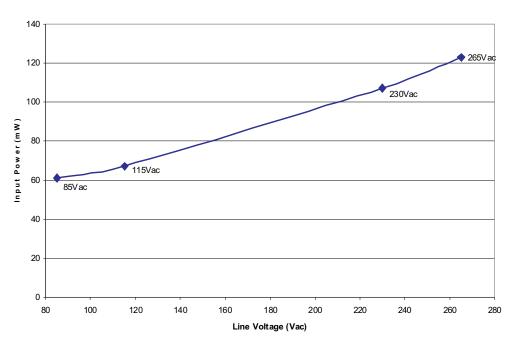


Figure 7. No-Load Input Power as a Function of Input Voltage



#### FB CURRENT vs. DRV CURRENT

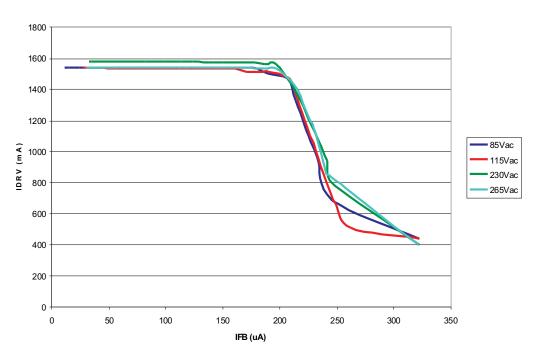


Figure 8. DRV Current as a Function of FB Current

#### FB CURRENT vs. SWITCHING FREQUENCY

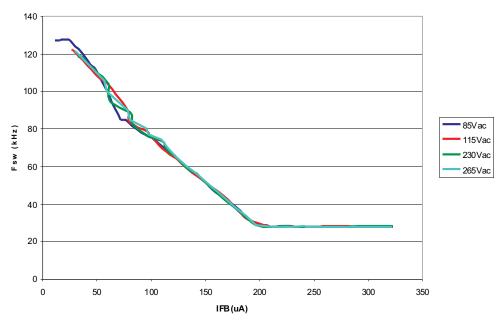


Figure 9. Switching Frequency as a Function of FB Current



#### **OUTPUT VOLTAGE vs LOAD CURRENT**

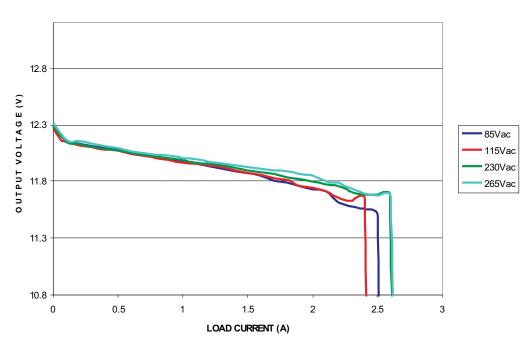


Figure 10. Output Voltage as a Function of Load Current and Line Voltage (Note the shutdown/retry threshold for each line voltage.)

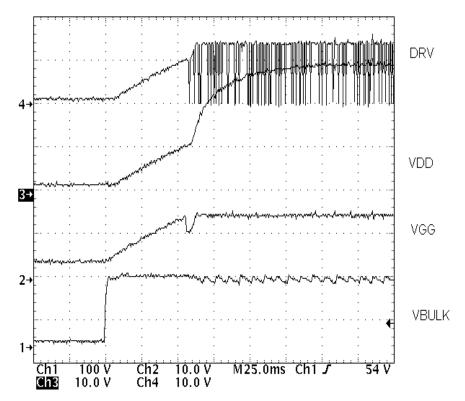


Figure 11. Start-Up Waveform (Input voltage = 115  $V_{AC}$ , full load. Ch.1 = bulk input voltage, 100 V/div., Ch.2 = VGG, 10 V/div., Ch.3 = VDD, 10V/div., Ch.4 = DRV, 10V/div.)



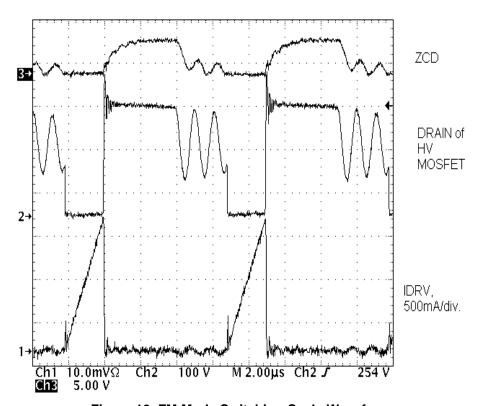


Figure 12. FM Mode Switching Cycle Waveform (Input voltage = 115  $V_{AC}$ , full load,  $f_{SW}$  = 112 kHz. Ch.1 =  $I_{DRV}$ , 500 mA/div.,  $I_{DRV}$  = 1.53 A, Ch.2 = Drain of HV MOSFET, 100 V/div., Ch.3 = ZCD, 5 V/div.)

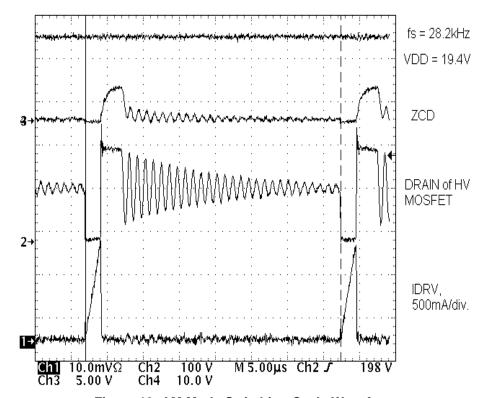


Figure 13. AM Mode Switching Cycle Waveform (Input voltage = 85  $V_{AC}$ , 0.3-A load,  $f_{SW}$  = 28.2 kHz, Ch.1 =  $I_{DRV}$ , 500 mA/div.,  $I_{DRV}$  = 1.1 A, Ch.2 = Drain of HV MOSFET, 100 V/div., Ch.3 = ZCD, 5 V/div., Ch. 4 = VDD, 10 V/div.)



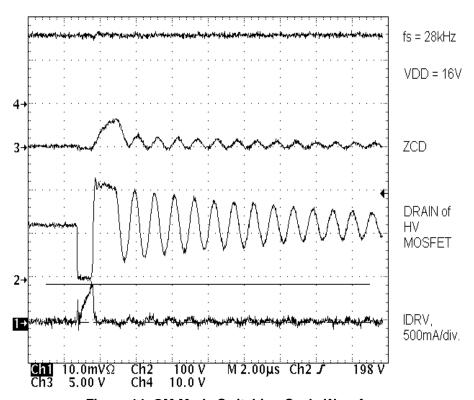


Figure 14. GM Mode Switching Cycle Waveform (Input voltage = 85  $V_{AC}$ , 0-A load,  $f_{SW}$  = 28 kHz, Ch.1 =  $I_{DRV}$ , 500 mA/div.,  $I_{DRV}$  = 440 mA, Ch.2 = Drain of HV MOSFET, 100 V/div., Ch.3 = ZCD, 5 V/div., Ch. 4 = VDD, 10 V/div.)

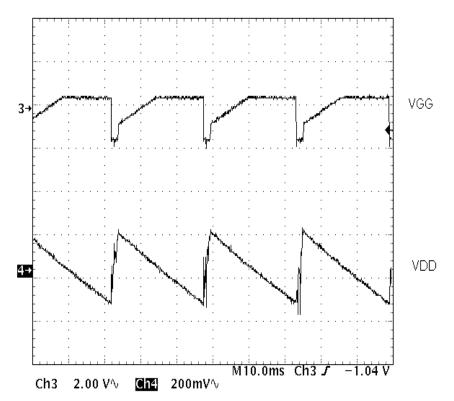


Figure 15. Ripple on VGG and VDD During Green Mode Operation (Ch.3 = VGG, AC coupled, 2 V/div., Ch.4 = VDD, AC coupled, 200 mV/div.)



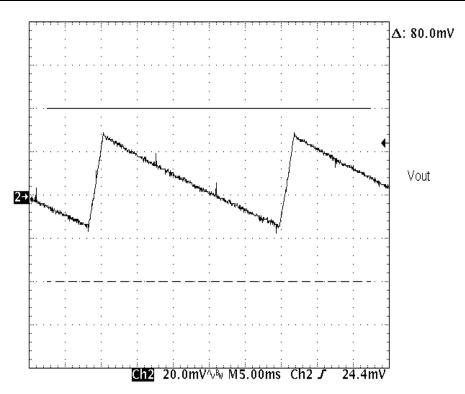


Figure 16. Output Voltage Ripple During Green Mode Operation (Input voltage = 85  $V_{AC}$ , no load. Ch.2 =  $V_{OUT}$ , AC coupled, 20 mV/div.)

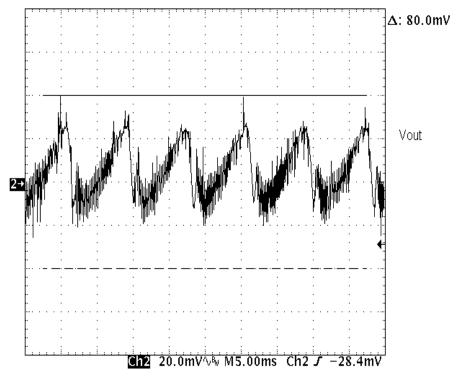


Figure 17. Output Voltage Ripple During Frequency Modulation Mode (Input voltage = 85  $V_{AC}$ , full load. Ch.2 =  $V_{OUT}$ , AC coupled, 20 mV/div.)



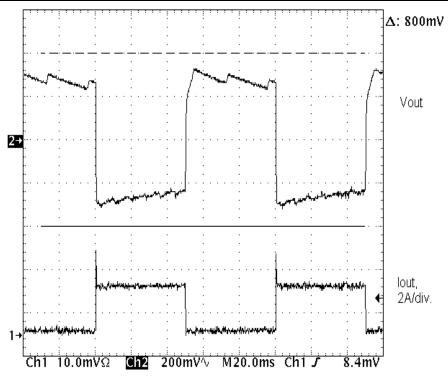


Figure 18. Load Transient, 0% to 100% Load Step (Ch.1 =  $I_{OUT}$ , 2 A/div., Ch.2 =  $V_{OUT}$ , AC coupled, 200 mV/div.)

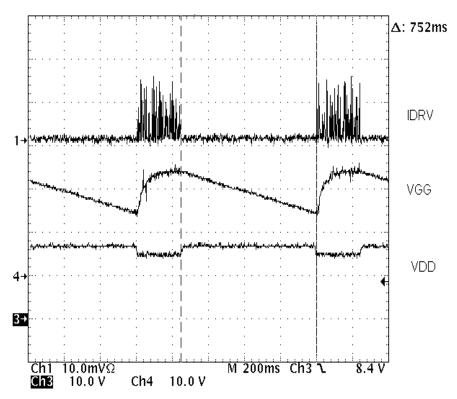


Figure 19. Brown-Out Protection (MOT shutdown/retry response triggered at full load when input voltage dropped to 72.4  $V_{AC}$ . Note the 750-ms  $t_{RETRY}$ . Ch.1 =  $I_{DRV}$ , Ch.3 = VDD, 10 V/div., Ch.4 = VGG, 10 V/div.)



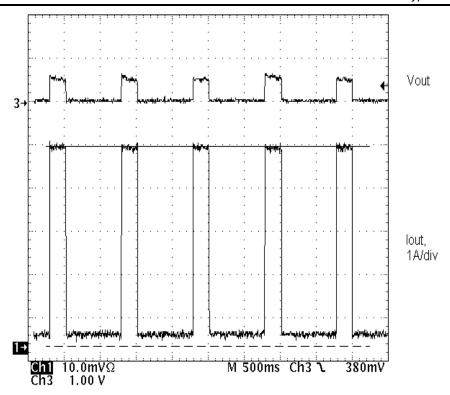


Figure 20. Output Short Circuit Protection (Short circuit maintained on output; note the output current goes to 4.62 A, refer to equation 13 in the data sheet, during the 250-ms delay to overload fault,  $t_{\text{OL}}$ , and retries after  $t_{\text{RETRY}}$  = 750 ms. Input voltage = 85  $V_{\text{AC}}$ . Ch.1 =  $I_{\text{OUT}}$ , 1 A/div., Ch. 3 =  $V_{\text{OUT}}$ , 1 V/div.)

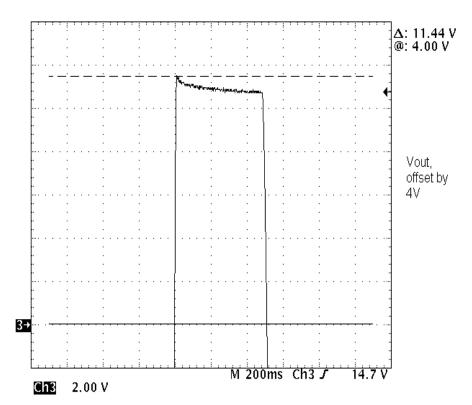


Figure 21. Output Over Voltage Protection (The EVM was tested with an open FB loop, no load. OVP threshold is equal to 15.44 V. Ch.  $3 = V_{OUT}$ , 2 V/div., offset by 4 V.)



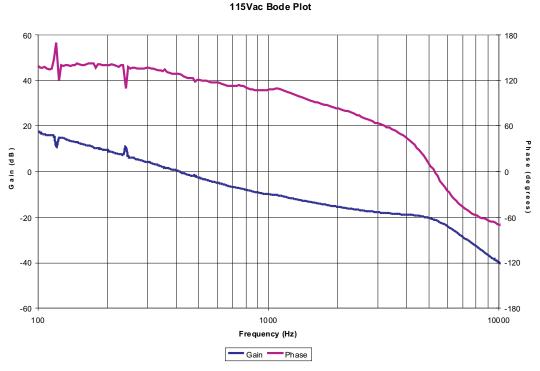


Figure 22. Bode Plot (Input voltage = 115  $V_{AC}$ , full load.)

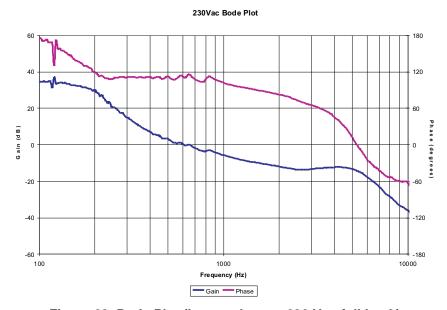


Figure 23. Bode Plot (Input voltage = 230  $V_{AC}$ , full load.)



## 8 EVM Assembly Drawing and Layout

Figure 24 through Figure 26 show the design of the UCC28610EVM-474 printed circuit board.

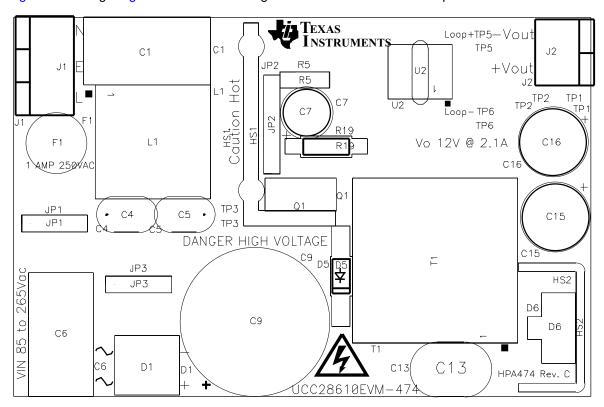


Figure 24. Top Layer Component Placement



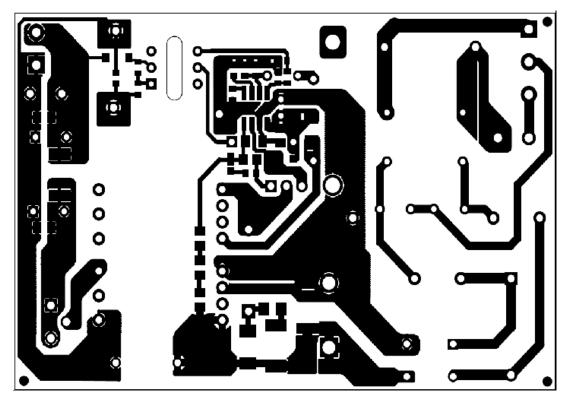


Figure 25. Bottom Layer Routing

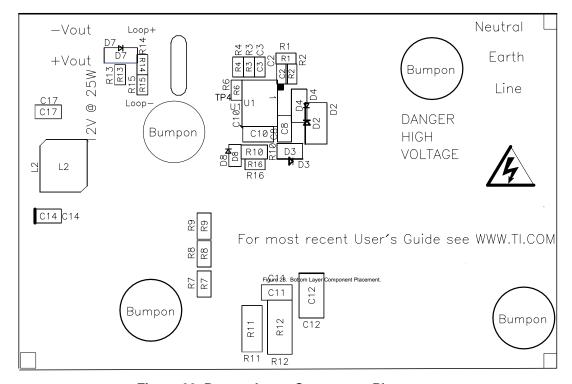


Figure 26. Bottom Layer Component Placement



www.ti.com List of Materials

#### 9 **List of Materials**

## Table 3. List of Materials for UCC28610EVM-474

2         C1, C6         Capacitor, Imn, 0.33 μF, 275 VAC, X2, ±20%, 0.690 x 0.374 inch         ECQ-U2A334ML         Panasonic           1         C2         Capacitor, ceramic, 100 pF, 50 V, NP0, ±5%, 0603         Std         Std         Std           0         C3         Capacitor, ceramic, not populated, 50 V, NP0, ±5%, 0603         Std         Std         Std           2         C4, C5 (optional)         Capacitor, ceramic, 2200 pF, 250 VAC, X1/Y2, ±20%, 0.315 x 0.200 inch         DE2E3KY222MA2BM01         muRata           1         C7         Capacitor, ceramic, 0.1 μF, 50 V, X7R, ±10%, 0805         ECU-FC1V680         Panasonic           1         C8         Capacitor, ceramic, 0.1 μF, 50 V, X7R, ±10%, 0805         ECU-FC1V680         Panasonic           1         C9         Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 0805         Std         Std         Std           1         C10         Capacitor, ceramic, 330 PF, 630 V, COG, NPO, ±5%, 1206         Std         Std         Std           1         C11         Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, 234 V, 345 inch         ECK-ANA102MB         Panasonic           2         C14, C17         Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, 234 V, 345 inch         ECK-ANA102MB         Panasonic           2         C15, C16         Capacitor, aluminum el	COUNT	REF DES	DESCRIPTION	PART NUMBER	MFR
0         C3         Capacitor, ceramic, not populated, 50 V, NP0, ±5%, 603         Std         Std         Std           2         C4, C5 (optional)         Capacitor, ceramic, 2200 pF, 250 VAC, X1/Y2, ±20%, 0.315 x 0.200 inch         DE2E3KY222MA2BM01         muRata           1         C7         Capacitor, aluminum electrolytic, 68 μF, 35 V, ±20%, 0.200 inch         EEU-FC1V680         Panasonic           1         C8         Capacitor, ceramic, 0.1 μF, 50 V, X7R, ±10%, 0805         CC0805KRX7R9BB104         Yageo Corporation           1         C9         Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 0805         Std         Std         Std           1         C10         Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 1206         Std         Std         Std           1         C11         Capacitor, ceramic, 330 pF, 630 V, C0G, NP0, ±5%, 1206         Std         Std         Std           1         C12         Capacitor, ceramic, 0.1 μF, 630 V, X7R, ±10%, 1812         C4532X7R2J104K         TDK Corporation           2         C14, C17         Capacitor, ceramic, 1 μF, 25 V, X5R, ±10%, 0805         Std         Std           2         C14, C17         Capacitor, aluminum electrolytic, 680 μF, 25 V, ±20%, 10 kg and 10 kg	2	C1, C6		ECQ-U2A334ML	Panasonic
0         G603         Std         Std           2         C4, C5 (optional)         Capacitor, ceramic, 2200 pF, 250 VAC, X1/Y2, ±20%, (optional)         DE2E3KY222MA2BM01         muRata           1         C7         Capacitor, aluminum electrolytic, 68 μF, 35 V, ±20%, 20 k; 20 k; 20 k; 20 mm         EEU-FC1V680         Panasonic           1         C8         Capacitor, ceramic, 0.1 μF, 50 V, X7R, ±10%, 0805         CC0805KRX7R9BB104         Yageo Corporation           1         C9         Capacitor, aluminum electrolytic, 100 μF, 400 VDC, 20%, 25 x 20 mm         EET-HC2G101BA         Panasonic           1         C10         Capacitor, ceramic, 330 pF, 630 V, C0G, NPO, ±5%, 1206         Std         Std         Std           1         C11         Capacitor, ceramic, 0.1 μF, 630 V, X7R, ±10%, 1812         C4532X7R2J104K         TDK Corporation           1         C12         Capacitor, ceramic, 0.1 μF, 530 V, X7R, ±10%, 0805         Std         Std         Std           1         C13         Capacitor, ceramic, 0.1 μF, 530 V, X7R, ±10%, 0805         Std         Std         Std           1         C14         Capacitor, ceramic, 0.1 μF, 25 V, XSR, ±10%, 0805         Std         Std         Std           2         C14, C17         Capacitor, ceramic, 0.1 μF, 25 V, XSR, ±10%, 0805         Std         Std         <	1	C2	Capacitor, ceramic, 100 pF, 50 V, NP0, ±5%, 0603	Std	Std
Coptional   0.315 x 0.200 inch   Capacitor, aluminum electrolytic, 68 μF, 35 V, ±20%   EEU-FC1V680   Panasonic	0	C3		Std	Std
1 C7 0,200 inch 1 C8 Capacitor, ceramic, 0.1 μF, 50 V, X7R, ±10%, 0805 CC0805KRX7R9BB104 Yageo Corporation 1 C9 Capacitor, aluminum electrolytic, 100 μF, 400 VDC, ±20%, 25 x 20 mm 1 C10 Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 1206 Std Std Std 1 C11 Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 1206 Std Std Std 1 C12 Capacitor, ceramic, 0.1 μF, 630 V, C0G, NP0, ±5%, 1206 Std Std Std 1 C12 Capacitor, ceramic, 0.1 μF, 630 V, X7R, ±10%, 1812 C4532X7R2J104K TDK Corporation 1 C13 Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%	2	,		DE2E3KY222MA2BM01	muRata
1 C9 Capacitor, aluminum electrolytic, 100 μF, 400 VDC, ±20%, 25 x 20 mm 1 C10 Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 1206 Std Std Std 1 C11 Capacitor, ceramic, 330 pF, 630 V, C0G, NP0, ±5%, 1206 Std Std Std 1 C12 Capacitor, ceramic, 0.1 μF, 630 V, X7R, ±10%, 1812 C4532X7R2J104K TDK Corporation 1 C13 Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, ECK-ANA102MB Panasonic 2 C14, C17 Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, ECK-ANA102MB Panasonic 2 C14, C17 Capacitor, ceramic, 1 μF, 25 V, X5R, ±10%, 0805 Std Std Std 2 C15, C16 Capacitor, aluminum electrolytic, 680 μF, 25 V, ±20%, 10 x 25 mm Diode, bridge, 1 A, 600 V DF06M Diodes Inc. 1 D1 Diode, bridge, 1 A, 600 V DF06M Diodes Inc. 1 D2 Diode, ultra fast, 1 A, 200 V, SMA MURA120T3G On Semiconductor 1 D3 Diode, schottky, 100 mA, 40 V, SOD-323 RB501V-40TE-17 Rohm Semiconductor 1 D4 Diode, Zener, 25 V, 500 mW, SOD-123 MMSZ5253BT1G On Semiconductor 1 D5 Diode, fast recovery glass passivated, 1 A, 1 kV, UF4007-TP Micro Commercial Co. 1 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics 1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor 1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG 1 F1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch S9211000410 Wickmann 1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch HS001 NH Stamp 1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Urter Colletronics Inch	1	C7		EEU-FC1V680	Panasonic
1 C10 Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 1206 Std Std Std Std C1206 Capacitor, ceramic, 0.1 μF, 100 V, X7R, ±10%, 1206 Std	1	C8	Capacitor, ceramic, 0.1 µF, 50 V, X7R, ±10%, 0805	CC0805KRX7R9BB104	Yageo Corporation
1 C11 Capacitor, ceramic, 330 pF, 630 V, C0G, NP0, ±5%, 1206 1 C12 Capacitor, ceramic, 0.1 μF, 630 V, X7R, ±10%, 1812 C13 Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, 0.394 x 0.315 inch C13 Capacitor, ceramic, 1 μF, 25 V, X5R, ±10%, 0805 C14, C17 Capacitor, ceramic, 1 μF, 25 V, X5R, ±10%, 0805 C15, C16 Capacitor, aluminum electrolytic, 680 μF, 25 V, ±20%, 10 x 25 mm D1 Diode, bridge, 1 A, 600 V DF06M Diodes Inc. D2 Diode, ultra fast, 1 A, 200 V, SMA MURA120T3G On Semiconductor D3 Diode, schottky, 100 mA, 40 V, SOD-323 RB501V-40TE-17 Rohm Semiconductor D4 Diode, Zener, 25 V, 500 mW, SOD-123 MMSZ5253BT1G On Semiconductor D5 Diode, fast recovery glass passivated, 1 A, 1 kV, DO-41 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor MMSZ5240B Fairchild Semiconductor MMSZ5240B Fairchild Semiconductor Littlefluse / Wickmann MMSZ5240B HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS2 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch HCP0703-3R3-R Colltronics/Cooper	1	C9		EET-HC2G101BA	Panasonic
1 C12 Capacitor, ceramic, 0.1 μF, 630 V, X7R, ±10%, 1812 C4532X7R2J104K TDK Corporation  1 C13 Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, 0.394 x 0.315 inch  2 C14, C17 Capacitor, ceramic, 1 μF, 25 V, X5R, ±10%, 0805 Std Std  2 C15, C16 Capacitor, aluminum electrolytic, 680 μF, 25 V, ±20%, 10 x 25 mm  1 D1 Diode, bridge, 1 A, 600 V DF06M Diodes Inc.  1 D2 Diode, ultra fast, 1 A, 200 V, SMA MURA120T3G On Semiconductor  1 D3 Diode, schottky, 100 mA, 40 V, SOD-323 RB501V-40TE-17 Semiconductor  1 D4 Diode, Zener, 25 V, 500 mW, SOD-123 MMSZ5253BT1G On Semiconductor  1 D5 Diode, fast recovery glass passivated, 1 A, 1 kV, UF4007-TP Micro Commercial Co.  1 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics  1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor  1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG  1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann  1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch S07302B00000 Aavid Thermalloy  1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp  1 L1 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 HCP0703-3R3-R Coiltronics/Cooper	1	C10	Capacitor, ceramic, 0.1 µF, 100 V, X7R, ±10%, 1206	Std	Std
1 C13 Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, 0.394 x 0.315 inch  2 C14, C17 Capacitor, ceramic, 1 μF, 25 V, X5R, ±10%, 0805 Std Std  2 C15, C16 Capacitor, aluminum electrolytic, 680 μF, 25 V, ±20%, 10 x 25 mm  1 D1 Diode, bridge, 1 A, 600 V DF06M Diodes Inc.  1 D2 Diode, ultra fast, 1 A, 200 V, SMA MURA120T3G On Semiconductor  1 D3 Diode, schottky, 100 mA, 40 V, SOD-323 RB501V-40TE-17 Rohm Semiconductor  1 D4 Diode, Zener, 25 V, 500 mW, SOD-123 MMSZ5253BT1G On Semiconductor  1 D5 Diode, fast recovery glass passivated, 1 A, 1 kV, UF4007-TP Micro Commercial Co.  1 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics  1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor  1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG  1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann  1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch HS00 HS00 Aavid Thermalloy  1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS00 NH Stamp  1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch HCP0703-3R3-R Coiltronics/Cooper	1	C11		Std	Std
1 C13	1	C12	Capacitor, ceramic, 0.1 µF, 630 V, X7R, ±10%, 1812	C4532X7R2J104K	TDK Corporation
2 C15, C16 Capacitor, aluminum electrolytic, 680 μF, 25 V, ±20%, 10 x 25 mm  D1 Diode, bridge, 1 A, 600 V  DF06M  Diodes Inc.  D2 Diode, ultra fast, 1 A, 200 V, SMA  MURA120T3G  On Semiconductor  Rohm Semiconductor  D3 Diode, schottky, 100 mA, 40 V, SOD-323  RB501V-40TE-17  Rohm Semiconductor  D4 Diode, Zener, 25 V, 500 mW, SOD-123  D5 Diode, fast recovery glass passivated, 1 A, 1 kV, UF4007-TP  D6 Diode, dual Schottky, 20 A, 100 V, TO-220  D7 Diode, Zener, 10 V, 500 mW, SOD-123  MMSZ5240B  Fairchild Semiconductor  D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2  MA21D3400L  Panasonic - SSG  MA21D3400L  Panasonic - SSG  Litelfluse / Wickmann  HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch  HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch  HS0 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch  L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch  HCP0703-3R3-R  Coiltronics/Cooper	1	C13		ECK-ANA102MB	Panasonic
2         C15, C16         10 x 25 mm         EEU-FM1E681         Panasonic           1         D1         Diode, bridge, 1 A, 600 V         DF06M         Diodes Inc.           1         D2         Diode, ultra fast, 1 A, 200 V, SMA         MURA120T3G         On Semiconductor           1         D3         Diode, schottky, 100 mA, 40 V, SOD-323         RB501V-40TE-17         Rohm Semiconductor           1         D4         Diode, Zener, 25 V, 500 mW, SOD-123         MMSZ5253BT1G         On Semiconductor           1         D5         Diode, fast recovery glass passivated, 1 A, 1 kV, DO-41         UF4007-TP         Micro Commercial Co.           1         D6         Diode, dual Schottky, 20 A, 100 V, TO-220         STPS20H100CT         STMicroelectronics           1         D7         Diode, Zener, 10 V, 500 mW, SOD-123         MMSZ5240B         Fairchild Semiconductor           1         D8         Diode, Schottky barrier, 1 A, 30 V, SMini2-F2         MA21D3400L         Panasonic - SSG           1         F1         Fuse, slow blow, 1 A, 250 V, 0.335 inch         38211000410         Littelfuse / Wickmann           1         HS1         Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch         507302B00000         Aavid Thermalloy           1         HS2         Heatsink, alloy 1110 copper, 0.530 x 1	2	C14, C17	Capacitor, ceramic, 1 µF, 25 V, X5R, ±10%, 0805	Std	Std
1 D2 Diode, ultra fast, 1 A, 200 V, SMA MURA120T3G On Semiconductor 1 D3 Diode, schottky, 100 mA, 40 V, SOD-323 RB501V-40TE-17 Rohm Semiconductor 1 D4 Diode, Zener, 25 V, 500 mW, SOD-123 MMSZ5253BT1G On Semiconductor 1 D5 Diode, fast recovery glass passivated, 1 A, 1 kV, UF4007-TP Micro Commercial Co. 1 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics 1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor 1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG 1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann 1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy 1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp 1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Urice Electronics Corp. 1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch	2	C15, C16		EEU-FM1E681	Panasonic
1 D3 Diode, schottky, 100 mA, 40 V, SOD-323 RB501V-40TE-17 Rohm Semiconductor 1 D4 Diode, Zener, 25 V, 500 mW, SOD-123 MMSZ5253BT1G On Semiconductor 1 D5 Diode, fast recovery glass passivated, 1 A, 1 kV, DO-41 UF4007-TP Micro Commercial Co. 1 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics 1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor 1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG 1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann 1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy 1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp 1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Uriter Electronics Corp. 1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch HCP0703-3R3-R Coiltronics/Cooper	1	D1	Diode, bridge, 1 A, 600 V	DF06M	Diodes Inc.
1 D3 Diode, Scholiky, 100 HIA, 40 V, SOD-323 RBS01V-401E-17 Semiconductor  1 D4 Diode, Zener, 25 V, 500 mW, SOD-123 MMSZ5253BT1G On Semiconductor  1 D5 Diode, fast recovery glass passivated, 1 A, 1 kV, DO-41 UF4007-TP Micro Commercial Co.  1 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics  1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor  1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG  1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann  1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy  1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp  1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Urice Electronics Corp.  1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch	1	D2	Diode, ultra fast, 1 A, 200 V, SMA	MURA120T3G	On Semiconductor
1 D5 Diode, fast recovery glass passivated, 1 A, 1 kV, DO-41 UF4007-TP Micro Commercial Co.  1 D6 Diode, dual Schottky, 20 A, 100 V, TO-220 STPS20H100CT STMicroelectronics  1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor  1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG  1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littleffuse / Wickmann  1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy  1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp  1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Corp.  1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch HCP0703-3R3-R Coiltronics/Cooper	1	D3	Diode, schottky, 100 mA, 40 V, SOD-323	RB501V-40TE-17	
DO-41	1	D4	Diode, Zener, 25 V, 500 mW, SOD-123	MMSZ5253BT1G	On Semiconductor
1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Fairchild Semiconductor  1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG  1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann  1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy  1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp  1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Using Corp.  1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 inch HCP0703-3R3-R Coiltronics/Cooper	1	D5		UF4007-TP	
1 D7 Diode, Zener, 10 V, 500 mW, SOD-123 MMSZ5240B Semiconductor  1 D8 Diode, Schottky barrier, 1 A, 30 V, SMini2-F2 MA21D3400L Panasonic - SSG  1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann  1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy  1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp  1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Using Corp.  1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 HCP0703-3R3-R Coiltronics/Cooper	1	D6	Diode, dual Schottky, 20 A, 100 V, TO-220	STPS20H100CT	STMicroelectronics
1 F1 Fuse, slow blow, 1 A, 250 V, 0.335 inch 38211000410 Littelfuse / Wickmann  1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy  1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp  1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Vitec Electronics Corp.  1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 HCP0703-3R3-R Coiltronics/Cooper	1	D7	Diode, Zener, 10 V, 500 mW, SOD-123	MMSZ5240B	
1 HS1 Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch 507302B00000 Aavid Thermalloy 1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp 1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch Corp. 1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 HCP0703-3R3-R Coiltronics/Cooper	1	D8	Diode, Schottky barrier, 1 A, 30 V, SMini2-F2	MA21D3400L	Panasonic - SSG
1 HS2 Heatsink, alloy 1110 copper, 0.530 x 1.200 inch HS001 NH Stamp  1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch S4P512-276 Vitec Electronics Corp.  1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 HCP0703-3R3-R Coiltronics/Cooper	1	F1	Fuse, slow blow, 1 A, 250 V, 0.335 inch	38211000410	
1 L1 Inductor, AC line, common choke, 2 7 mH, 1 A, 0.660 x 0.670 inch  L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 HCP0703-3R3-R Coiltronics/Cooper	1	HS1	Heatsink, TO-220, vertical-mount, 0.5 x 0.750 inch	507302B00000	Aavid Thermalloy
1 L1 0.670 inch 54P512-276 Corp.  1 L2 Inductor, high current choke, 3.3 μH, 0.276 x 0.288 HCP0703-3R3-R Coiltronics/Cooper	1	HS2	Heatsink, alloy 1110 copper, 0.530 x 1.200 inch	HS001	NH Stamp
inch HCP0703-3R3-R Colltronics/Cooper	1	L1		54P512-276	
1 Q1 MOSFET, Nch, 600 V, 6 A, SC-67 2SK3562 Toshiba	1	L2		HCP0703-3R3-R	Coiltronics/Cooper
	1	Q1	MOSFET, Nch, 600 V, 6 A, SC-67	2SK3562	Toshiba



References www.ti.com

## Table 3. List of Materials for UCC28610EVM-474 (continued)

COUNT	REF DES	DESCRIPTION	PART NUMBER	MFR
1	R1	Resistor, chip, 100 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R2	Resistor, chip, 20.5 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R3	Resistor, chip, 51.1 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R4	Resistor, chip, 64.9 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R5	Resistor, metal film, 169 k $\Omega$ , 1/2 W, ±1%, 0.300 x 0.100 inch	SFR16S0001693FR500	Vishay/BC Components
1	R6	Resistor, chip, 68.1 kΩ, 1/10 W, ±1%, 0603	Std	Std
3	R7, R8, R9	Resistor, chip, 2.05MΩ, 1/8 W, 150V, ±1%, 0805	CRCW08052M05FKEA	Vishay/Dale
1	R10	Resistor, chip, 15.4 Ω, 1/8 W, ±1%, 0805	Std	Std
1	R11	Resistor, chip, 64.9 kΩ, 1/2 W, ±1%, 2010	Std	Std
1	R12	Resistor, chip, 33.2 Ω, 1 W, ±5%, 2512	Std	Std
1	R13	Resistor, chip, 20.5 Ω, 1/10 W, ±1%, 0603	Std	Std
1	R14	Resistor, chip, 1.00 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R15	Resistor, chip, 681 Ω, 1/10 W, ±1%, 0603	Std	Std
1	R16	Resistor, chip, 0 Ω, 1/10 W, ±1%, 0603	Std	Std
1	R19	Resistor, metal film, 1.00 kΩ, 1/4 W, ±1%, TH-400	Std	Std
1	T1	Transformer, flyback, 220 µH, PQ20/20	58P6936	Vitec Electronics
1	U1	Green-mode flyback controller, SO-8	UCC28610D	Texas Instruments
1	U2	Optocoupler, CTR 40% - 80%, 70 Vceo, 5000 V <sub>RMS</sub> , DIP6	CNY17F1M	Fairchild Optoelectronics

## 10 References

- 1. UCC28610 Green-Mode Flyback Controller, Datasheet, (TI Literature Number SLUS888)
- 2. Standby and Low Power Measurements, VOLTECHNOTES, VPN 104-054/1, http://www.voltech.com/Downloads/PMAppNotes/Low%20Power%20Standby.pdf



## Appendix A

## A.1 UCC28610EVM-474 Rev. A

The following schematic, board layout, and list of materials apply to the UCC28610EVM-474 Rev. A version of the evaluation module. The Rev. A version of the EVM includes differential mode inductors L2 and L3. Subsequent revisions of the EVM replaced these inductors with a short circuit.

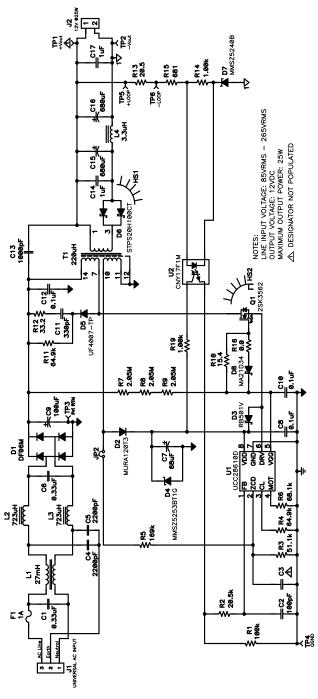


Figure 27. UCC28610EVM-474 Rev. A Schematic



UCC28610EVM-474 Rev. A www.ti.com

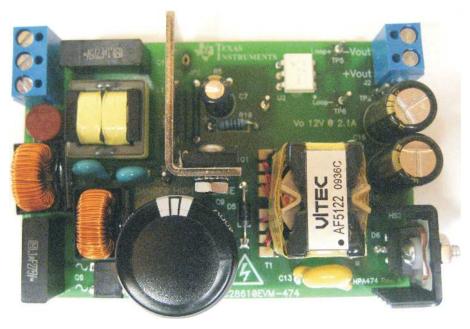


Figure 28. Top Side View of UCC28610EVM-474 Rev. A

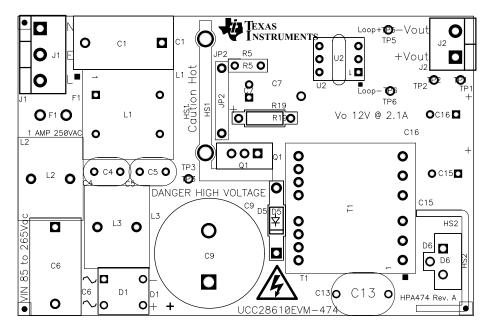
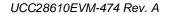


Figure 29. Top Layer Component Placement for UCC28610EVM-474 Rev. A





www.ti.com

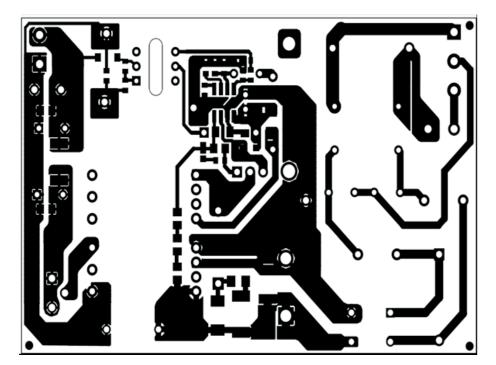


Figure 30. Bottom Layer Routing of UCC28610EVM-474 Rev. A

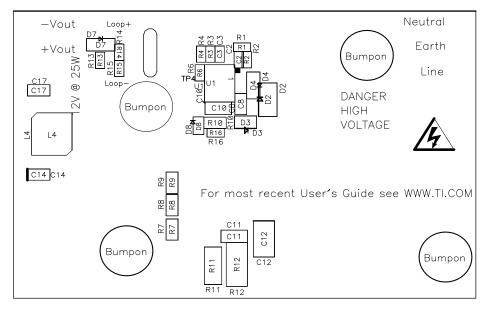


Figure 31. Bottom Layer Component Placement of UCC28610EVM-474 Rev. A



UCC28610EVM-474 Rev. A www.ti.com

## Table 4. Table 4. List of Materials for UCC28610EVM-474 Rev. A

COUNT	REF DES	DESCRIPTION	PART NUMBER	MFR
2	C1, C6	Capacitor, film, 0.33 μF, 275VAC, X2, ±20%, 0.690 x 0.374 inch	ECQ-U2A334ML	Panasonic
1	C2	Capacitor, ceramic, 100 pF, 50 V, NP0, ±5%, 0603	Std	Std
0	C3	Capacitor, ceramic, not populated, 50 V, NP0, ±5%, 0603	Std	Std
2	C4, C5 (optional)	Capacitor, ceramic, 2200 pF, 250 VAC, X1/Y2, ±20%, 0.315 x 0.200 inch	DE2E3KY222MA2BM 01	muRata
1	C7	Capacitor, aluminum electrolytic, 68 µF, 35 V, ±20%, 0.200 inch	EEU-FC1V680	Panasonic
1	C8	Capacitor, ceramic, 0.1 µF, 50 V, X7R, ±10%, 0805	CC0805KRX7R9BB10 4	Yageo Corporation
1	C9	Capacitor, aluminum electrolytic, 100 $\mu$ F, 400 VDC, ±20%, 25 x 20 mm	EET-HC2G101BA	Panasonic
1	C10	Capacitor, ceramic, 0.1 µF, 100 V, X7R, ±10%, 1206	Std	Std
1	C11	Capacitor, ceramic, 330 pF, 630 V, C0G, NP0, ±5%, 1206	Std	Std
1	C12	Capacitor, ceramic, 0.1 µF, 630 V, X7R, ±10%, 1812	C4532X7R2J104K	TDK Corporation
1	C13	Capacitor, ceramic disk, 1000 pF, 250 V, Y1/X1, ±20%, 0.394 x 0.315 inch	ECK-ANA102MB Panasonic	
2	C14, C17	Capacitor, ceramic, 1 µF, 25 V, X5R, ±10%, 0805	Std	Std
2	C15, C16	Capacitor, aluminum electrolytic, 680 µF, 25 V, ±20%, 10 x 25 mm	EEU-FM1E681	Panasonic
1	D1	Diode, bridge, 1 A, 600 V	DF06M	Diodes Inc.
1	D2	Diode, ultra fast, 1 A, 200 V, SMA	MURA120T3G	On Semiconductor
1	D3	Diode, Schottky, 100 mA, 40 V, SOD-323	RB501V-40TE-17	Rohm Semiconductor
1	D4	Diode, Zener, 500 mW, 25 V, SOD-123	MMSZ5253BT1G	On Semiconductor
1	D5	Diode, fast recovery glass passivated, 1 A, 1 kV, DO-41	UF4007-TP	Micro Commercial Co.
1	D6	Diode, dual Schottky, 20 A, 100 V, TO-220	STPS20H100CT	STMicroelectronics
1	D7	Diode, Zener, 10 V, 500 mW, SOD-123	MMSZ5240B	Fairchild Semiconductor
1	D8	Diode, Schottky barrier, 1 A, 30 V, SMini2-F2	MA21D3400L	Panasonic - SSG
1	F1	Fuse, slow blow, 1 A, 250 V, 0.335 inch	38211000410	Littelfuse / Wickmann
1	HS1	Heatsink, TO-220, vertical mount, 0.5 x 0.750 inch	507302B00000 Aavid Thermalloy	
1	HS2	Heatsink, alloy 1110 copper, 0.530 x 1.200 inch	HS001	NH Stamp
1	L1	Inductor, AC line, common choke, 27 mH, 1 A, 0.660 x 0.670 inch	54P512-276	Vitec Electronics Corp.
2	L2, L3	Inductor, EMI, 723 $\mu$ H, 0.620 $\Omega$ , ±15%, 11.94 x 15.49 mm	54P2986	Vitec Electronics Corp.
1	L4	Inductor, high current choke, 3.3 µH, 0.276 x 0.288 inch	HCP0703-3R3-R	Coiltronics/Cooper
1	Q1	MOSFET, N-channel, 600 V, 6A, SC-67	2SK3562	Toshiba



www.ti.com UCC28610EVM-474 Rev. A

## Table 4. Table 4. List of Materials for UCC28610EVM-474 Rev. A (continued)

COUNT	REF DES	DESCRIPTION	PART NUMBER	MFR
1	R1	Resistor, chip, 100 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R2	Resistor, chip, 20.5 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R3	Resistor, chip, 51.1 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R4	Resistor, chip, 64.9 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R5	Resistor, metal film, 169 k $\Omega$ , 1/2 W, ±1%, 0.300 x 0.100 inch	SFR16S0001693FR5 00	Vishay/BC Components
1	R6	Resistor, chip, 68.1 kΩ, 1/10 W, ±1%, 0603	Std	Std
3	R7, R8, R9	Resistor, chip, 2.05 MΩ, 1/8 W, 150 V, ±1%, 0805	CRCW08052M05FKE A	Vishay/Dale
1	R10	Resistor, chip, 15.4 W, 1/8 W, ±1%, 0805	Std	Std
1	R11	Resistor, chip, 64.9 kΩ, 1/2 W, ±1%, 2010	Std	Std
1	R12	Resistor, chip, 33.2 Ω, 1 W, ±5%, 2512	Std	Std
1	R13	Resistor, chip, 20.5 Ω, 1/10 W, ±1%, 0603	Std	Std
1	R14	Resistor, chip, 1.00 kΩ, 1/10 W, ±1%, 0603	Std	Std
1	R15	Resistor, chip, 681 Ω, 1/10 W, ±1%, 0603	Std	Std
1	R16	Resistor, chip, 0 Ω, 1/10 W, ±1%, 0603	Std	Std
1	R19	Resistor, metal film, 1.00 kΩ, 1/4 W, ±1%, TH-400	Std	Std
1	T1	Transformer, flyback, 220 µH, PQ20/20	58P6936	Vitec Electronics
1	U1	Green-Mode Flyback Controller, SO-8	UCC28610D	Texas Instruments
1	U2	Optocoupler, CTR 40% - 80%, 70 Vceo, 5000Vrms, DIP6	CNY17F1M	Fairchild Optoelectronics



UCC28610EVM-474 Rev. A www.ti.com

#### **EVALUATION BOARD/KIT IMPORTANT NOTICE**

Texas Instruments (TI) provides the enclosed product(s) under the following conditions:

This evaluation board/kit is intended for use for **ENGINEERING DEVELOPMENT**, **DEMONSTRATION**, **OR EVALUATION PURPOSES ONLY** and is not considered by TI to be a finished end-product fit for general consumer use. Persons handling the product(s) must have electronics training and observe good engineering practice standards. As such, the goods being provided are not intended to be complete in terms of required design-, marketing-, and/or manufacturing-related protective considerations, including product safety and environmental measures typically found in end products that incorporate such semiconductor components or circuit boards. This evaluation board/kit does not fall within the scope of the European Union directives regarding electromagnetic compatibility, restricted substances (RoHS), recycling (WEEE), FCC, CE or UL, and therefore may not meet the technical requirements of these directives or other related directives.

Should this evaluation board/kit not meet the specifications indicated in the User's Guide, the board/kit may be returned within 30 days from the date of delivery for a full refund. THE FOREGOING WARRANTY IS THE EXCLUSIVE WARRANTY MADE BY SELLER TO BUYER AND IS IN LIEU OF ALL OTHER WARRANTIES, EXPRESSED, IMPLIED, OR STATUTORY, INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR ANY PARTICULAR PURPOSE.

The user assumes all responsibility and liability for proper and safe handling of the goods. Further, the user indemnifies TI from all claims arising from the handling or use of the goods. Due to the open construction of the product, it is the user's responsibility to take any and all appropriate precautions with regard to electrostatic discharge.

EXCEPT TO THE EXTENT OF THE INDEMNITY SET FORTH ABOVE, NEITHER PARTY SHALL BE LIABLE TO THE OTHER FOR ANY INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES.

TI currently deals with a variety of customers for products, and therefore our arrangement with the user is not exclusive.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein.

Please read the User's Guide and, specifically, the Warnings and Restrictions notice in the User's Guide prior to handling the product. This notice contains important safety information about temperatures and voltages. For additional information on TI's environmental and/or safety programs, please contact the TI application engineer or visit www.ti.com/esh.

No license is granted under any patent right or other intellectual property right of TI covering or relating to any machine, process, or combination in which such TI products or services might be or are used.

## **FCC Warning**

This evaluation board/kit is intended for use for **ENGINEERING DEVELOPMENT, DEMONSTRATION, OR EVALUATION PURPOSES ONLY** and is not considered by TI to be a finished end-product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC rules, which are designed to provide reasonable protection against radio frequency interference. Operation of this equipment in other environments may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

#### **EVM WARNINGS AND RESTRICTIONS**

It is important to operate this EVM within the input voltage range of 85  $V_{AC}$  to 265  $V_{AC}$  and the output voltage of 12 V .

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 60 °C. The EVM is designed to operate properly with certain components above as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2010, Texas Instruments Incorporated

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
DSP	dsp.ti.com	Industrial	www.ti.com/industrial
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Security	www.ti.com/security
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Power Mgmt	<u>power.ti.com</u>	Transportation and Automotive	www.ti.com/automotive
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps
RF/IF and ZigBee® Solutions	www.ti.com/lprf		

TI E2E Community Home Page e2e.ti.com